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Form 1449*

**INFORMATION DISCLOSURE STATEMENT
BY APPLICANT
(Use several sheets if necessary)**

Atty. Docket No.: 303.648US1

Serial No. 09/484,303

Applicant: Kie Y. Ahn et al.

Filing Date: January 18, 2000

Group: 2823

U. S. PATENT DOCUMENTS

**Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
NB	5,371,042✓	12/06/1994	Ong, E.	437	194	06/16/92
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**Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation Yes No
NB	5-267643✓	10/15/1993	Japan			

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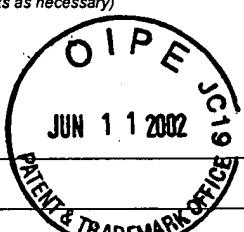
(Including Author, Title, Date, Pertinent Pages, Etc.)

**Examiner Initial

Examiner Neal Berezny | Date Considered 3-22-03

*Substitute Disclosure Statement Form (PTO-1449)

**EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

Substitute for form 1449A/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary)		Complete if Known Application Number 09/484303 Filing Date January 18, 2000 First Named Inventor Ahn, Kie Group Art Unit 2825 Examiner Name Unknown				
 Sheet 1 of 1		Attorney Docket No: 00303.648US1				

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EXAMINER

Neal Berenzny

DATE CONSIDERED

3-22-03